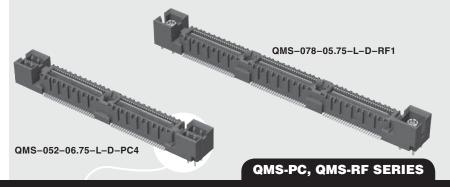




(0.635 mm) .025"



HIGH-SPEED COMBO RF & POWER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QMS

Insulator Material:

Liquid Crystal Polymer Terminal & Ground Plane Material:

Phosphor Bronze

Plating: Au over 50 μ" (1.27 μm) Ni

(Tin on Ground Plane Tail) Current Rating: Signal Contact: 2.6 A per pin

(2 pins powered) Power Contact:

4.0 A per pin (4 pins powered per end) Ground Plane:

15.7 A per ground plane (1 ground plane powered)
Voltage Rating:
300 VAC mated with QFS

Operating Temp: -55 °C to +125 °C **RoHS Compliant:** Yes

PROCESSING

Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max (026-078) **Board Stacking:**

For applications requiring more than two connectors per board, contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

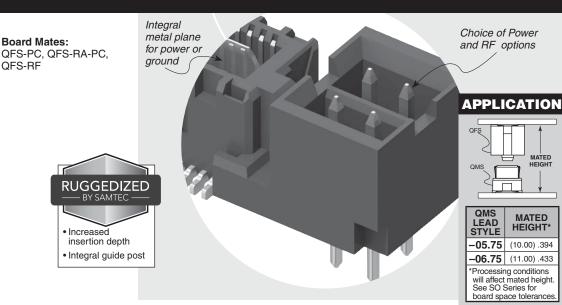


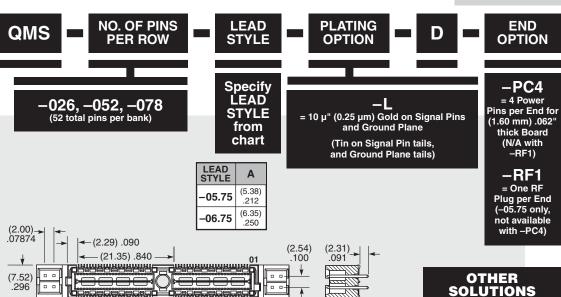
ALSO AVAILABLE (MOQ Required)

.296

- · Other platings
- Differential Pairs
- Retention Pins
- 8 Power Pins/End for (1.60 mm) 0.62" thick board
- · 4 or 8 Power Pins/End for (2.36 mm) .093" thick board
- 2 RF Connectors/End
- Hot Pluggable

Some lengths, styles and options are non-standard, non-returnable.





See SO Series for precision machined standoffs.

